



远勋
YUANXUN

YX100D170B6TC

1700V 100A IGBT Module

PRODUCT FEATURES

- High short circuit capability, self limiting short circuit current
- IGBT CHIP(Highly rugged SPT+ design)
- $V_{CE(sat)}$ with positive temperature coefficient
- Ultra Low Loss, High Ruggedness
- Free wheeling diodes with fast and soft reverse recovery



APPLICATIONS

- AC motor control
- Motion/servo control
- Inverter and power supplies
- Photovoltaic/Fuel cell

IGBT-inverter

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
V_{CES}	Collector Emitter Voltage	$T_J=25^\circ\text{C}$	1700	V
V_{GES}	Gate Emitter Voltage		± 20	
I_C	DC Collector Current	$T_C=25^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	150	A
		$T_C=100^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	100	
I_{CM}	Repetitive Peak Collector Current	$t_p=1\text{ms}$	200	
P_{tot}	Power Dissipation Per IGBT	$T_C=25^\circ\text{C}, T_{Jmax}=175^\circ\text{C}$	789	W

Diode-inverter

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
V_{RRM}	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1700	V
$I_{F(AV)}$	Average Forward Current		100	
I_{FRM}	Repetitive Peak Forward Current	$t_p=1\text{ms}$	200	A
I^2t		$T_J=150^\circ\text{C}, t=10\text{ms}, V_R=0\text{V}$	2600	



远勋
YUANXUN

IGBT-inverter

ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit	
$V_{GE(\text{th})}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}$, $I_C=4\text{mA}$	5.4	6.2	7.4	V	
$V_{CE(\text{sat})}$		$I_C=100\text{A}$, $V_{GE}=15\text{V}$, $T_J=25^\circ\text{C}$		2.3	2.7		
		$I_C=100\text{A}$, $V_{GE}=15\text{V}$, $T_J=125^\circ\text{C}$		2.65			
I_{CES}		$I_C=100\text{A}$, $V_{GE}=15\text{V}$, $T_J=150^\circ\text{C}$		2.7			
Collector Leakage Current	$V_{CE}=1700\text{V}$, $V_{GE}=0\text{V}$, $T_J=25^\circ\text{C}$			1	mA		
	$V_{CE}=1700\text{V}$, $V_{GE}=0\text{V}$, $T_J=150^\circ\text{C}$			10	mA		
I_{GES}	Gate Leakage Current	$V_{CE}=0\text{V}$, $V_{GE}=\pm 15\text{V}$, $T_J=25^\circ\text{C}$	-500		500	nA	
Q_g	Gate Charge	$V_{CE}=900\text{V}$, $I_C=100\text{A}$, $V_{GE}=\pm 15\text{V}$		0.9		µC	
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=1\text{MHz}$		7.3		nF	
C_{res}	Reverse Transfer Capacitance			0.28		nF	
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=900\text{V}$, $I_C=100\text{A}$ $R_G=10\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$		150	ns	
			$T_J=150^\circ\text{C}$		170	ns	
t_r	Rise Time		$T_J=25^\circ\text{C}$		105	ns	
			$T_J=150^\circ\text{C}$		110	ns	
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=900\text{V}$, $I_C=100\text{A}$ $R_G=10\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$		400	ns	
			$T_J=150^\circ\text{C}$		460	ns	
t_f	Fall Time		$T_J=25^\circ\text{C}$		180	ns	
			$T_J=150^\circ\text{C}$		310	ns	
E_{on}	Turn on Energy	$V_{CC}=900\text{V}$, $I_C=100\text{A}$ $R_G=10\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$		36	mJ	
			$T_J=125^\circ\text{C}$		45	mJ	
			$T_J=150^\circ\text{C}$		47.5	mJ	
E_{off}	Turn off Energy		$T_J=25^\circ\text{C}$		16	mJ	
			$T_J=125^\circ\text{C}$		25	mJ	
			$T_J=150^\circ\text{C}$		27.5	mJ	
I_{sc}	Short Circuit Current	$\text{tpsc} \leq 10\mu\text{s}$, $V_{GE}=15\text{V}$ $T_J=150^\circ\text{C}$, $V_{CC}=1000\text{V}$			320	A	
R_{thJC}	Junction to Case Thermal Resistance (Per IGBT)				0.19	K /W	

Diode-inverter

ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F=100\text{A}$, $V_{GE}=0\text{V}$, $T_J=25^\circ\text{C}$		1.75	2.3	V
		$I_F=100\text{A}$, $V_{GE}=0\text{V}$, $T_J=125^\circ\text{C}$		1.85		
		$I_F=100\text{A}$, $V_{GE}=0\text{V}$, $T_J=150^\circ\text{C}$		1.9		
t_{rr}	Reverse Recovery Time	$I_F=100\text{A}$, $V_R=900\text{V}$ $dI_F/dt=-1100\text{A}/\mu\text{s}$ $T_J=150^\circ\text{C}$		1000		ns
I_{RRM}	Max. Reverse Recovery Current			84		A
Q_{RR}	Reverse Recovery Charge			48.3		µC
E_{rec}	Reverse Recovery Energy			28.5		mJ
R_{thJCD}	Junction to Case Thermal Resistance (Per Diode)				0.31	K /W



远勋
YUANXUN

MODULE CHARACTERISTICS ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions	Values	Unit
$T_{J\max}$	Max. Junction Temperature	175	$^\circ\text{C}$
T_{Jop}	Operating Temperature	-40~150	
T_{stg}	Storage Temperature	-40~125	
V_{isol}	Isolation Breakdown Voltage	4000	V
CTI	Comparative Tracking Index	> 225	
Torque	to heatsink	3~5	Nm
	to terminal	2.5~5	Nm
Weight		300	g

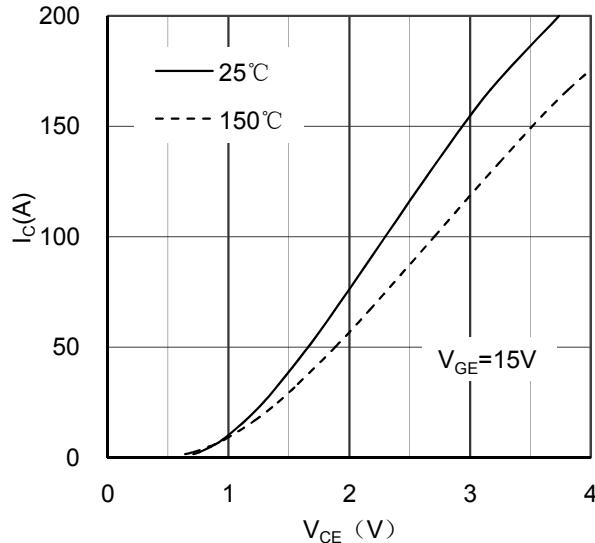


Figure 1. Typical Output Characteristics IGBT-inverter

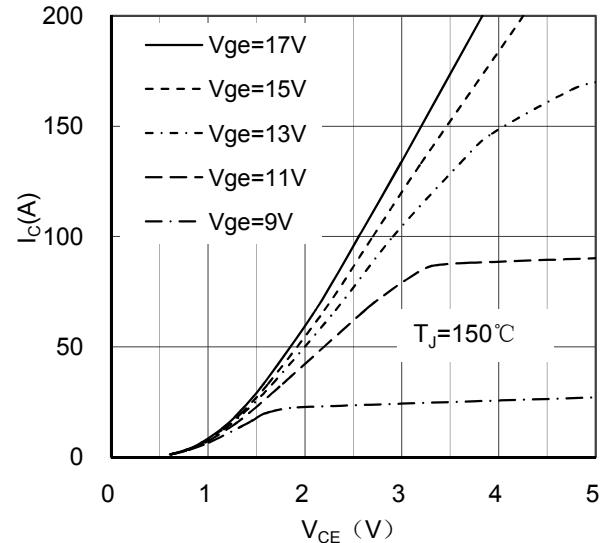


Figure 2. Typical Output Characteristics IGBT-inverter



远勋
YUANXUN

YX100D170B6TC

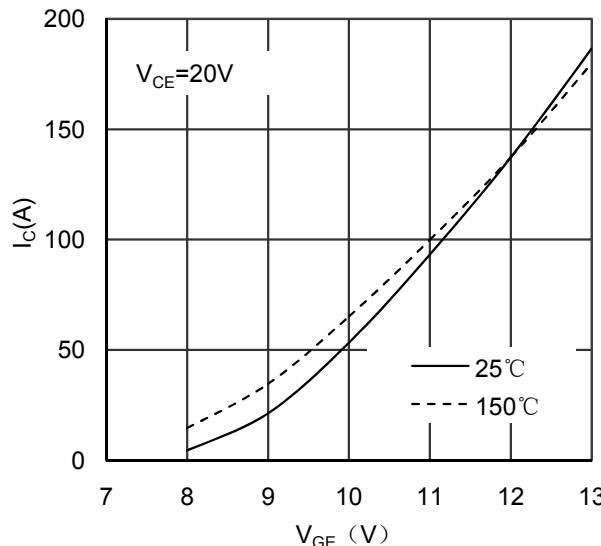


Figure 3. Typical Transfer characteristics IGBT-inverter

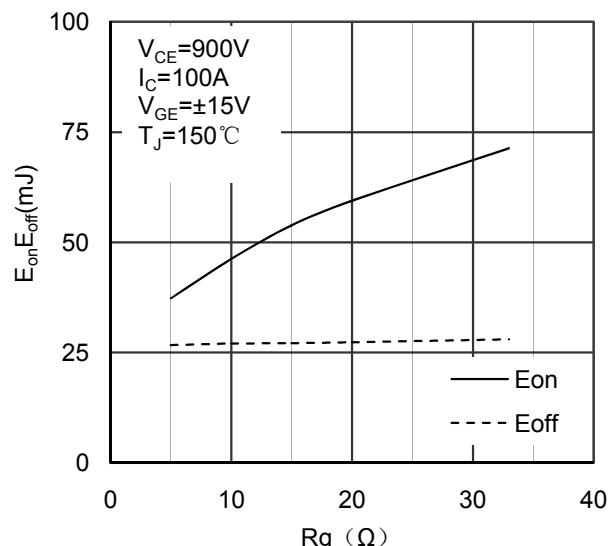


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

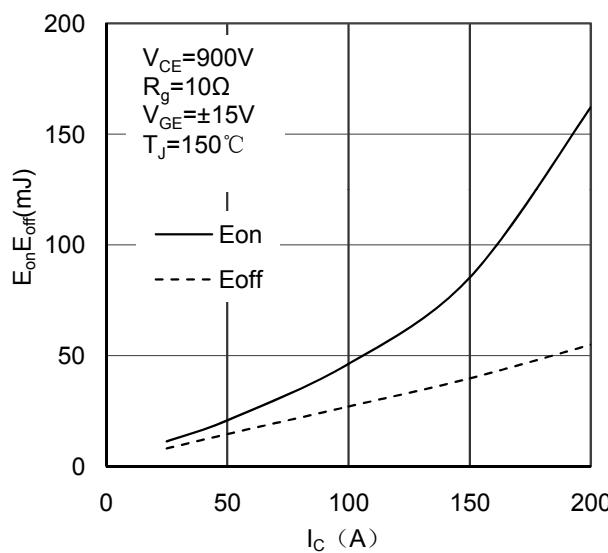


Figure 5. Switching Energy vs Collector Current IGBT-inverter

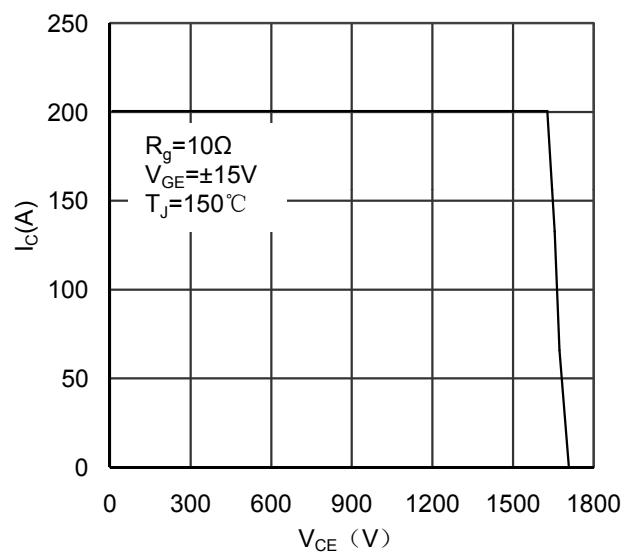


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

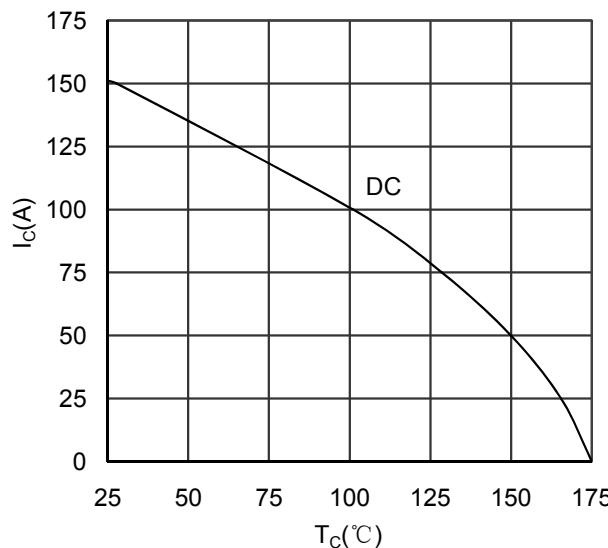


Figure 7. Collector Current vs Case temperature IGBT -inverter

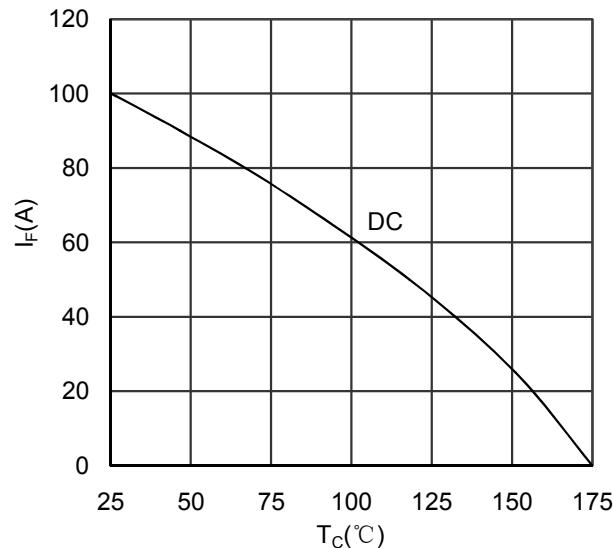


Figure 8. Forward current vs Case temperature Diode -inverter

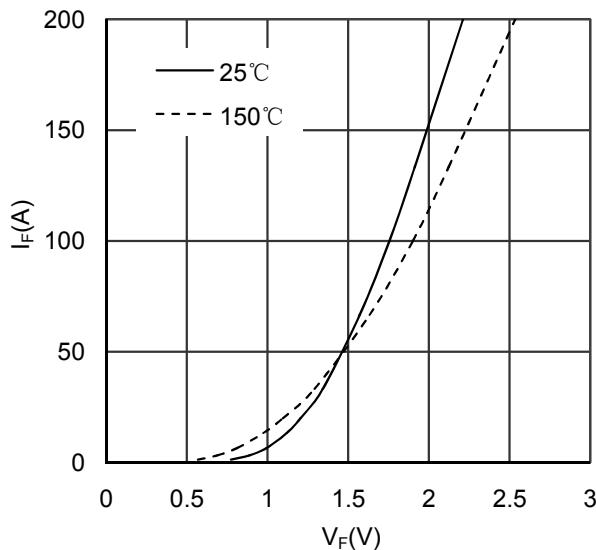


Figure 9. Diode Forward Characteristics Diode -inverter

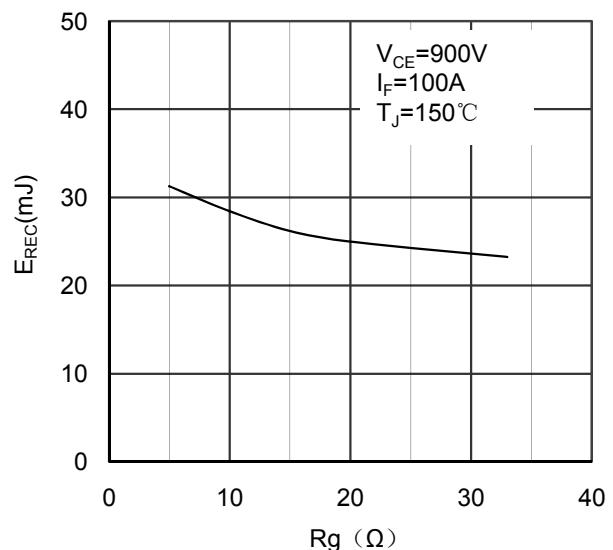


Figure 10. Switching Energy vs Gate Resistor Diode -inverter

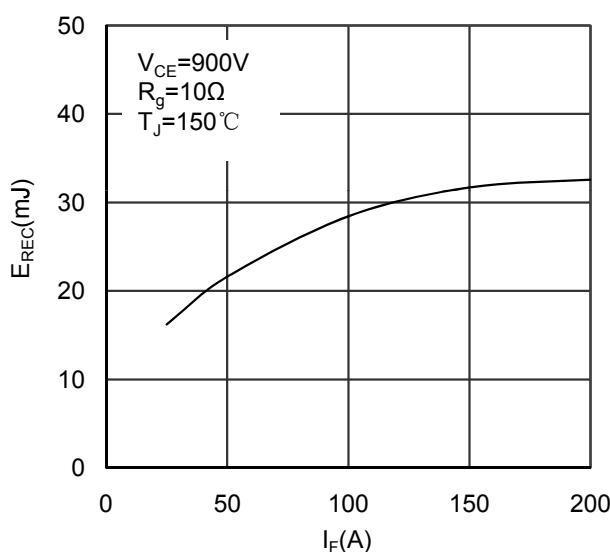


Figure 11. Switching Energy vs Forward Current Diode-inverter

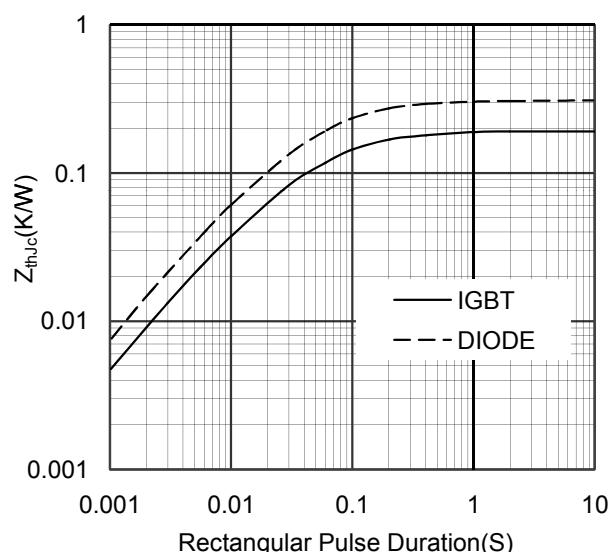


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter



远勋
YUANXUN

YX100D170B6TC

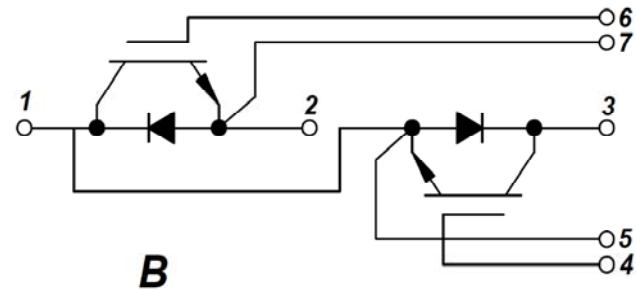
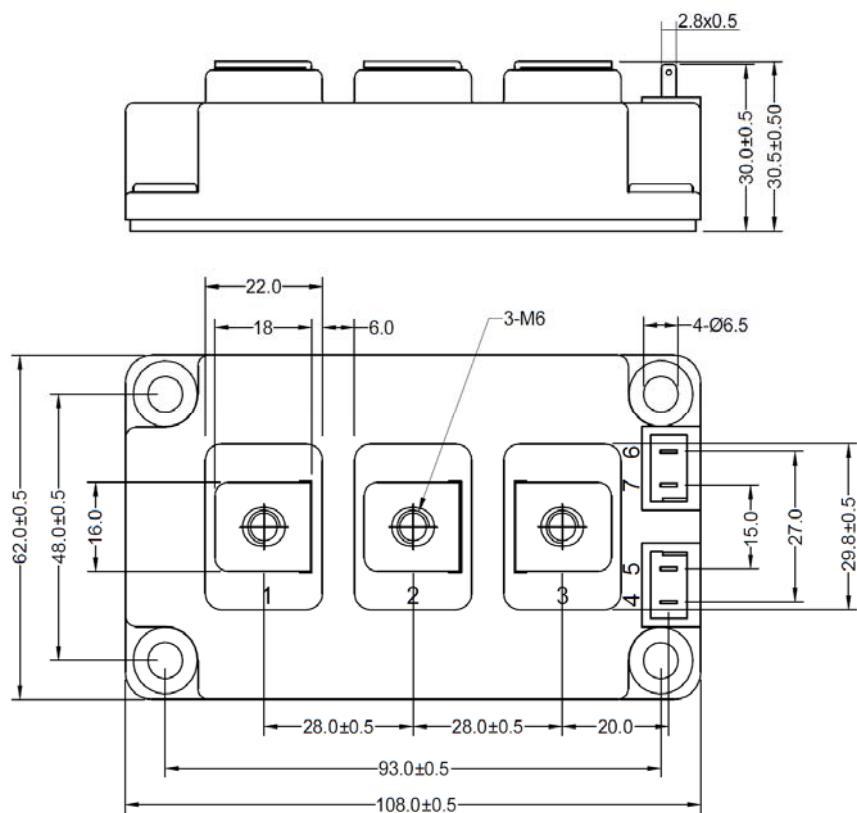


Figure 13. Circuit Diagram



Dimensions in (mm)

Figure 14. Package Outline